

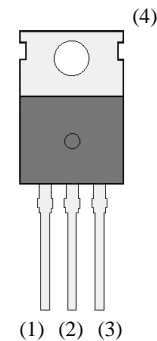
**75 V, 62 A, 7.2 mΩ Low RDS(ON)
N ch Trench Power MOSFET
EKI07117**

Features

- $V_{(BR)DSS}$ ----- 75 V ($I_D = 100 \mu A$)
- I_D ----- 62 A
- $R_{DS(ON)}$ ----- 9.7 mΩ max. ($V_{GS} = 10$ V, $I_D = 31.2$ A)
- Q_g ----- 25.0 nC ($V_{GS} = 4.5$ V, $V_{DS} = 38$ V, $I_D = 31.2$ A)
- Low Total Gate Charge
- High Speed Switching
- Low On-Resistance
- Capable of 4.5 V Gate Drive
- 100 % UIL Tested
- RoHS Compliant

Package

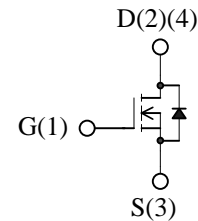
- TO220-3L



Not to scale

Applications

- DC-DC converters
- Synchronous Rectification
- Power Supplies



Absolute Maximum Ratings

- Unless otherwise specified, $T_A = 25^\circ C$

Parameter	Symbol	Test conditions	Rating	Unit
Drain to Source Voltage	V_{DS}		75	V
Gate to Source Voltage	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_C = 25^\circ C$	62	A
Pulsed Drain Current	I_{DM}	$PW \leq 100\mu s$ Duty cycle $\leq 1\%$	125	A
Continuous Source Current (Body Diode)	I_S		62	A
Pulsed Source Current (Body Diode)	I_{SM}	$PW \leq 100\mu s$ Duty cycle $\leq 1\%$	125	A
Single Pulse Avalanche Energy	E_{AS}	$V_{DD} = 38$ V, $L = 1$ mH, $I_{AS} = 11.2$ A, unclamped, $R_G = 4.7 \Omega$ Refer to Figure 1	126	mJ
Avalanche Current	I_{AS}		23.3	A
Power Dissipation	P_D	$T_C = 25^\circ C$	116	W
Operating Junction Temperature	T_J		150	$^\circ C$
Storage Temperature Range	T_{STG}		- 55 to 150	$^\circ C$

Thermal Characteristics

- Unless otherwise specified, $T_A = 25\text{ }^{\circ}\text{C}$

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Thermal Resistance (Junction to Case)	$R_{\theta JC}$		–	–	1.1	$^{\circ}\text{C/W}$
Thermal Resistance (Junction to Ambient)	$R_{\theta JA}$		–	–	62.5	$^{\circ}\text{C/W}$

Electrical Characteristics

- Unless otherwise specified, $T_A = 25\text{ }^{\circ}\text{C}$

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 100\text{ }\mu\text{A}$, $V_{GS} = 0\text{ V}$	75	–	–	V
Drain to Source Leakage Current	I_{DSS}	$V_{DS} = 75\text{ V}$, $V_{GS} = 0\text{ V}$	–	–	100	μA
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{ V}$	–	–	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 1\text{ mA}$	1.0	2.0	2.5	V
Static Drain to Source On-Resistance	$R_{DS(on)}$	$I_D = 31.2\text{ A}$, $V_{GS} = 10\text{ V}$	–	7.2	9.7	$\text{m}\Omega$
		$I_D = 15.6\text{ A}$, $V_{GS} = 4.5\text{ V}$	–	8.2	11.2	$\text{m}\Omega$
Gate Resistance	R_G	$f = 1\text{ MHz}$	–	1.1	–	Ω
Input Capacitance	C_{iss}	$V_{DS} = 25\text{ V}$ $V_{GS} = 0\text{ V}$ $f = 1\text{ MHz}$	–	4040	–	pF
Output Capacitance	C_{oss}		–	370	–	
Reverse Transfer Capacitance	C_{rss}		–	215	–	
Total Gate Charge ($V_{GS} = 10\text{ V}$)	Q_{g1}	$V_{DS} = 38\text{ V}$ $I_D = 31.2\text{ A}$	–	54.0	–	nC
Total Gate Charge ($V_{GS} = 4.5\text{ V}$)	Q_{g2}		–	25.0	–	
Gate to Source Charge	Q_{gs}		–	9.8	–	
Gate to Drain Charge	Q_{gd}		–	7.3	–	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 38\text{ V}$ $I_D = 31.2\text{ A}$ $V_{GS} = 10\text{ V}$, $R_G = 4.7\text{ }\Omega$ Refer to Figure 2	–	6.8	–	ns
Rise Time	t_r		–	6.4	–	
Turn-Off Delay Time	$t_{d(off)}$		–	29.4	–	
Fall Time	t_f		–	13.3	–	
Source to Drain Diode Forward Voltage	V_{SD}	$I_S = 31.2\text{ A}$, $V_{GS} = 0\text{ V}$	–	0.9	1.5	V
Source to Drain Diode Reverse Recovery Time	t_{rr}	$I_F = 31.2\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ Refer to Figure 3	–	44.3	–	ns
Source to Drain Diode Reverse Recovery Charge	Q_{rr}		–	69.1	–	nC

Test Circuits and Performance Curves

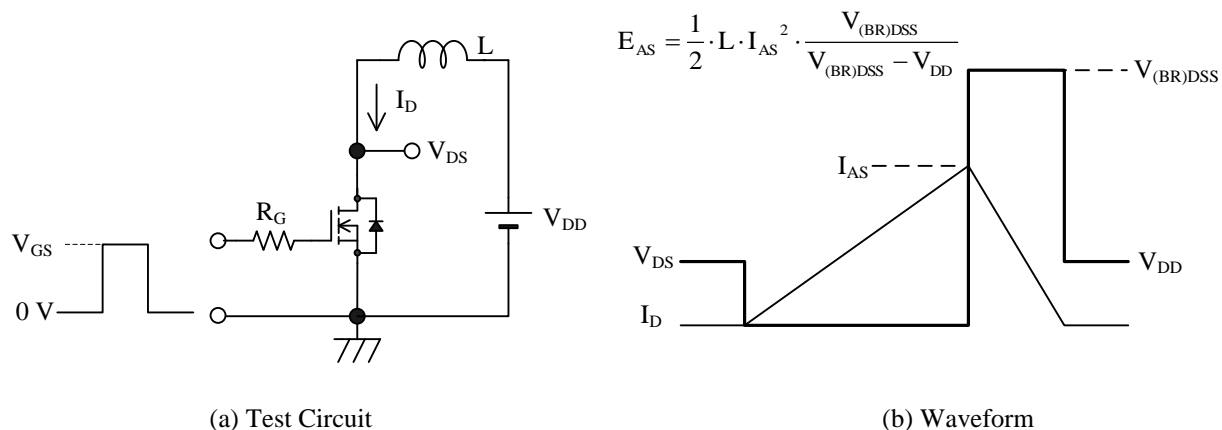


Figure 1. Unclamped Inductive Switching

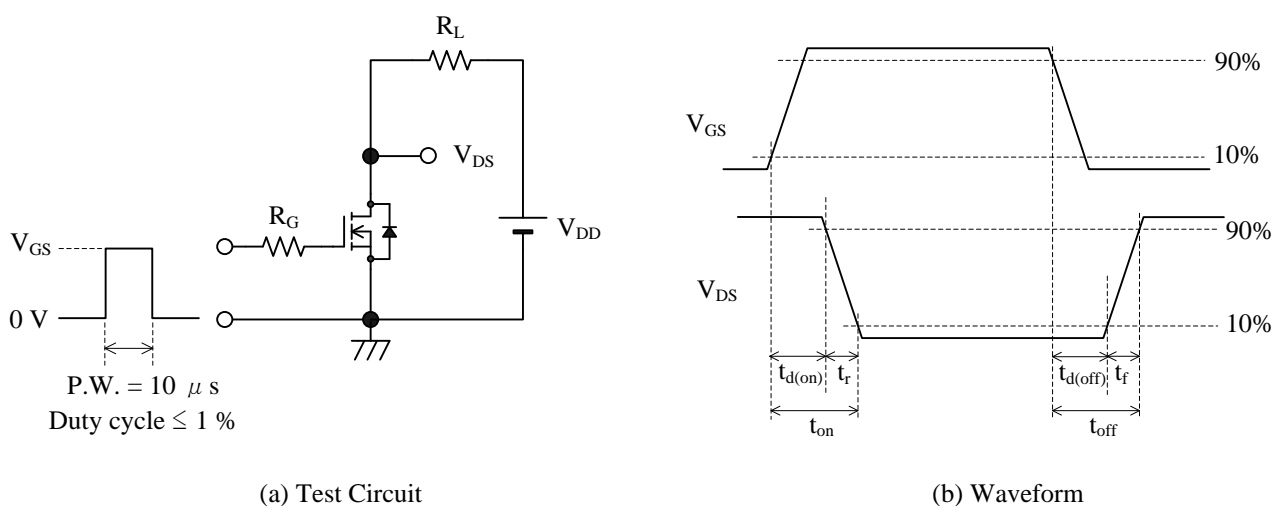


Figure 2. Switching Time

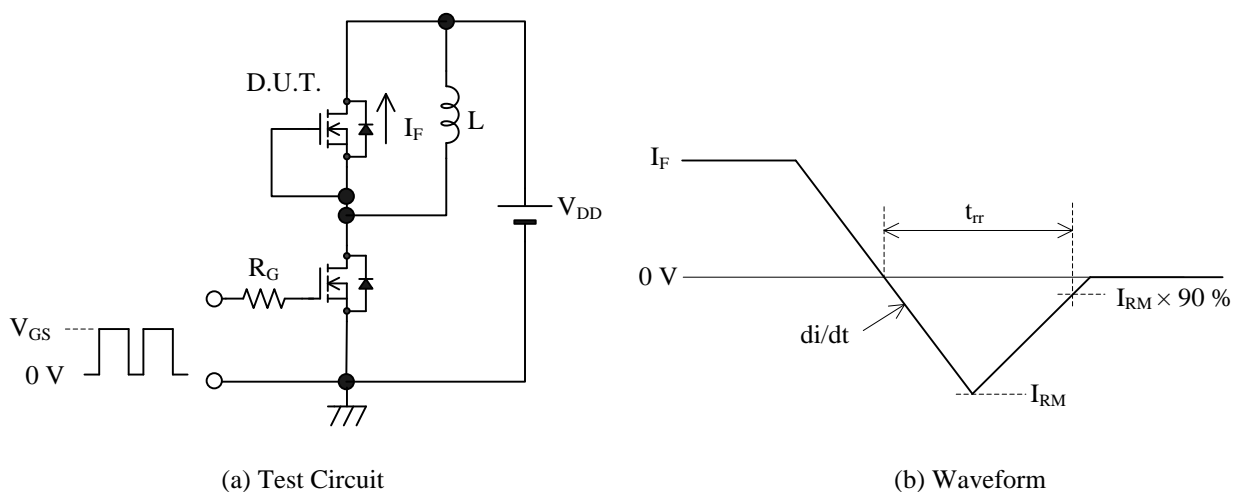
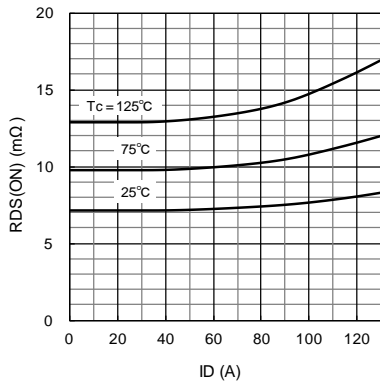
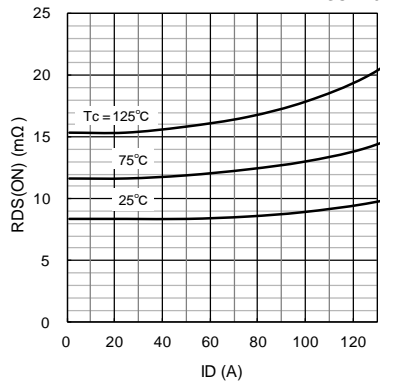


Figure 3. Diode Reverse Recovery Time

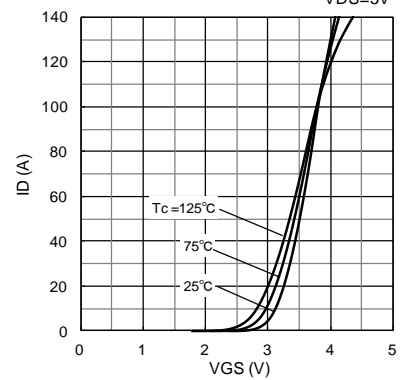
RDS(ON)-ID characteristics (typical)
VGS=10V



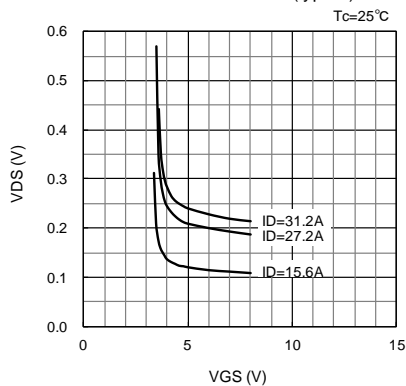
RDS(ON)-ID characteristics (typical)
VGS=4.5V



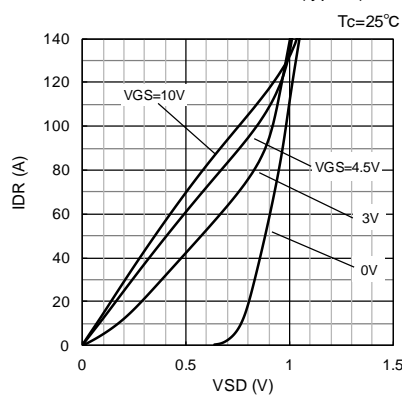
ID-VGS characteristics (typical)
VDS=5V



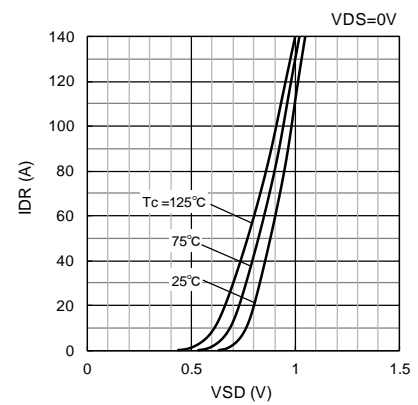
VDS-VGS characteristics (typical)
Tc=25°C



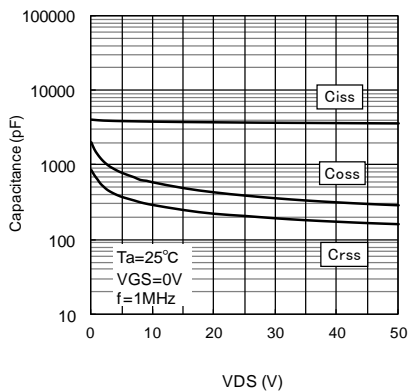
IDR-VSD characteristics (typical)
Tc=25°C



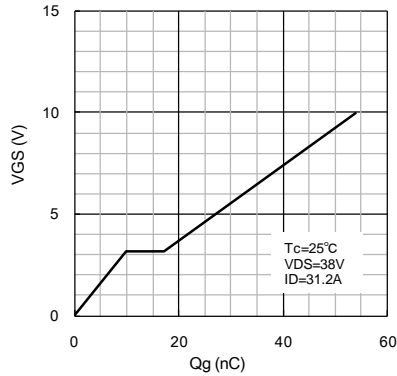
IDR-VSD characteristics (typical)
VDS=0V



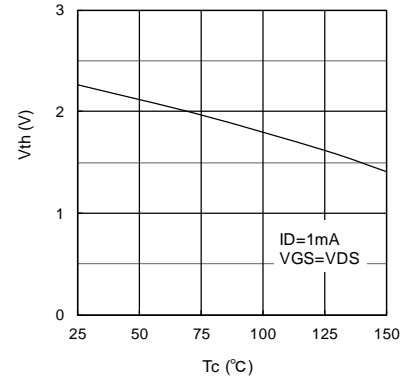
Capacitance-VDS characteristics (typical)



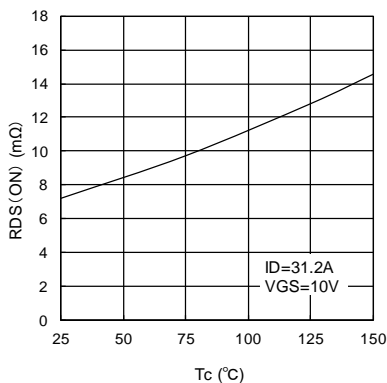
VGS - Qg characteristics (typical)



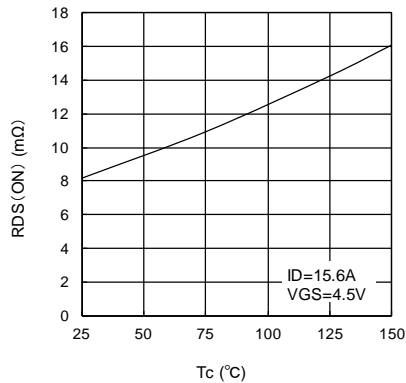
Vth-Tc characteristics (typical)



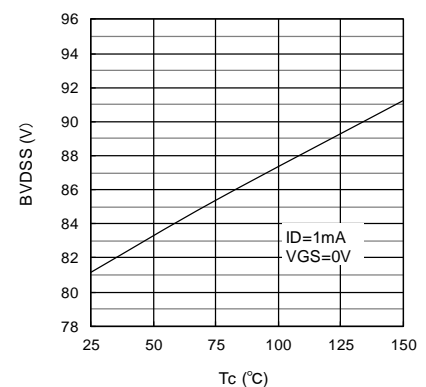
RDS(ON)-Tc characteristics (typical)

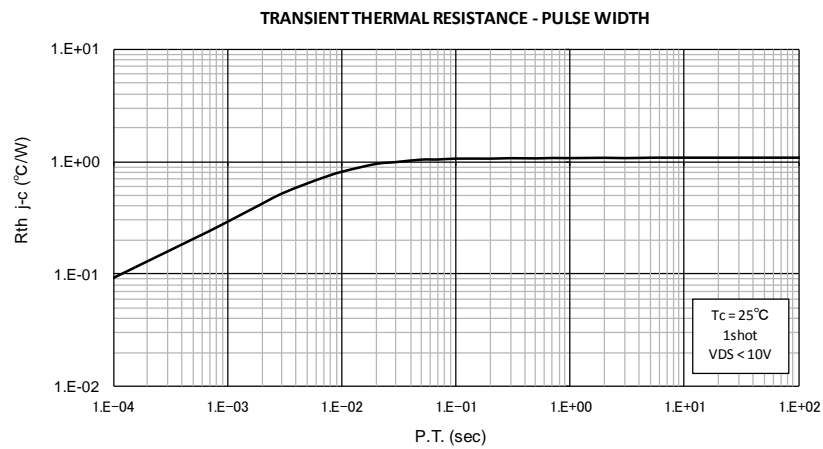
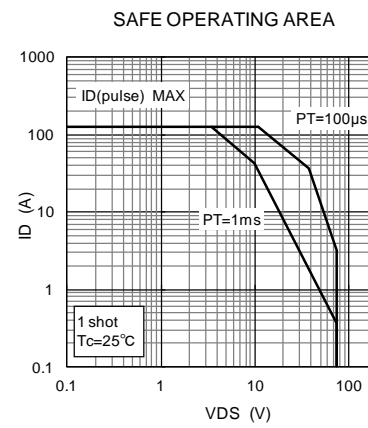
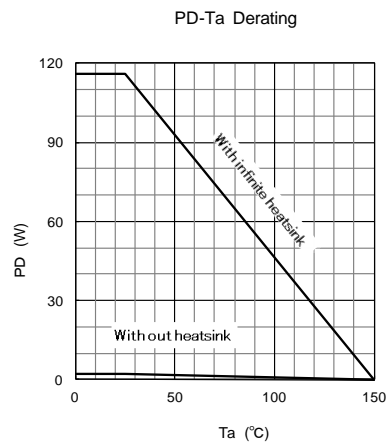


RDS(ON)-Tc characteristics (typical)



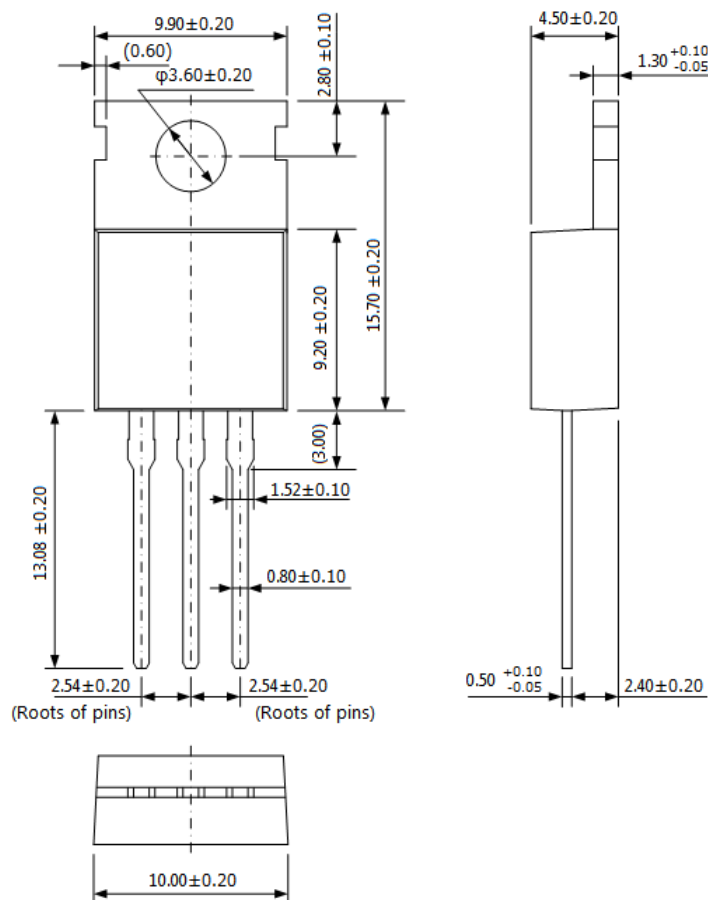
BVDSS-Tc characteristics (typical)





Physical Dimensions

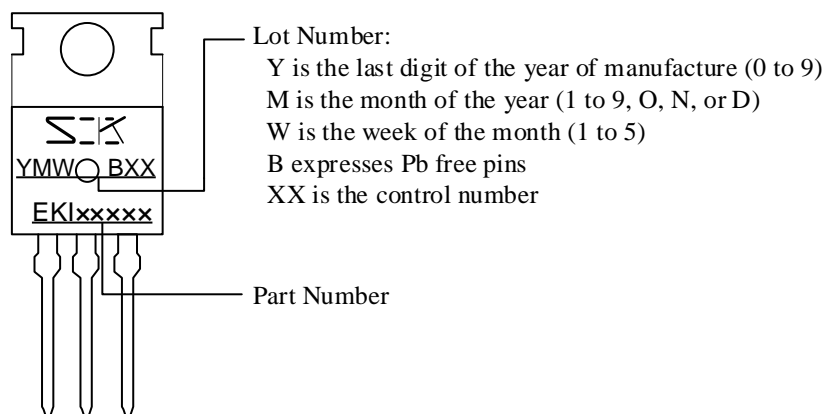
● TO220-3L



NOTES:

- Dimensions in millimeters
- Maximum gate burr height is 0.3 mm.
- Bare lead frame: Pb-free (RoHS compliant)
- When soldering the products, it is required to minimize the working time, within the following limits:
Flow: 260 ± 5 °C / 10 ± 1 s, 2 times
Soldering Iron: 380 ± 10 °C / 3.5 ± 0.5 s, 1 time
Soldering should be at a distance of at least 1.5 mm from the body of the product.
- Recommended screw torque for TO220: 0.490 N·m to 0.686 N·m (5 kgf·cm to 7 kgf·cm)

Marking Diagram



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